

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Application of

Alexander T. SCHWARM

Serial No. 10/759,108

Filed: January 20, 2004

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: Group Art Unit: 2825
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: Examiner:

For: AUTOMATED DESIGN AND EXECUTION OF EXPERIMENTS WITH
INTEGRATED MODEL CREATION FOR SEMICONDUCTOR MANUFACTURING
TOOLS

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

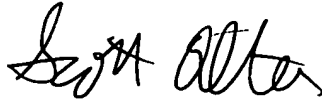
Serial No. 10/759,108

publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

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Date: 6/16/04

**INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)**ATTY. DOCKET NO.
008019 USA/MTCG/PCTRLSERIAL NO.
10/759,108APPLICANT
Alexander T. SCHWARMFILING DATE
January 20, 2004GROUP
2825**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	3,205,485	09/07/65	Noltingk			10/21/60
	3,229,198	01/11/66	Libby			09/28/62
	3,767,900	10/23/73	Chao et al.			06/23/71
	3,920,965	11/18/75	Sohrwardy			03/04/74
	4,000,458	12/28/76	Miller et al.			08/21/75
	4,207,520	06/10/80	Flora et al.			04/06/78
	4,209,744	06/24/80	Gerasimov et al.			03/27/78
	4,302,721	11/24/81	Urbanek et al.			05/15/79
	4,368,510	01/11/83	Anderson			10/20/80
	4,609,870	09/02/86	Lale et al.			09/13/84
	4,616,308	10/07/86	Morshedi et al.			12/02/85
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 008019 USA/MTCG/PCTRL		SERIAL NO. 10/759,108	
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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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	5,283,141	02/01/94	Yoon et al.			03/05/92	
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	5,923,553	07/13/99	Yi			10/05/96	
	5,926,690	07/20/99	Toprac et al.			05/28/97	
	5,930,138	07/27/99	Lin et al.			09/10/97	
	5,940,300	08/17/99	Ozaki			05/08/97	
	5,943,237	08/24/99	Van Boxem			10/17/97	
	5,960,185	09/28/99	Nguyen			06/24/96	
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96	
	5,961,369	10/05/99	Bartels et al.			06/04/98	
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	6,127,263	10/03/00	Parikh			07/10/98	
	6,128,016	10/03/00	Coelho et al.			12/20/96	
	6,136,163	10/24/00	Cheung et al.			03/05/99	
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	6,148,239	11/14/00	Funk et al.			12/12/97	
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	6,159,644	12/12/00	Satoh et al.			03/06/96	
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				FILING DATE January 20, 2004		GROUP 2825	
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12

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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
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	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems			
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide			
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow			
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	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions			
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	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing			
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
	10/173,108	06/18/02	Shanmugasundram et al.	Integrating Tool, Module, and Fab Level Control			
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	10/632,107	08/01/03	Schwarm et al.	Method, System, and Medium for Handling Misrepresentative Metrology Data Within an Advanced Process Control System			
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						Yes	No
	61-66104	04/04/86	Japan			X	
	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
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	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
	8-23166	01/23/96	Japan			X	
	08-50161	02/20/96	Japan			X	
	08-149583	06/07/96	Japan			X	
	08-304023	11/22/96	Japan			X	
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	09-34535	02/07/97	Japan			X	
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	WO 98/05066	02/05/98	WO			X	
	10-34522	02/10/98	Japan			X	
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	EP 0 869 652 A2	10/07/98	Europe			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 877 308 A2	11/11/98	Europe			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
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	EP 0 910 123 A1	04/21/99	Europe			X	
	11-126816	05/11/99	Japan			X	
	11-135601	05/21/99	Japan			X	
	WO 99/25520	05/27/99	WO			X	
	EP 0 932 194 A1	07/28/99	Europe			X	
	WO 99/59200	11/18/99	WO			X	
	WO 00/00874	01/06/00	WO			X	
	WO 00/05759	02/03/00	WO			X	
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	GB 2 347 885 A	09/20/00	United Kingdom			X	
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	WO 01/25865 A1	04/12/01	WO			X	
	EP 1 092 505 A2	04/18/01	Europe			X	
	WO 01/33277 A1	05/10/01	WO			X	
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	434103	05/16/01	Taiwan			X	
	436383B	05/28/01	Taiwan			X	
	WO 01/52055 A3	07/19/01	WO			X	
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	455976	09/21/01	Taiwan			X	
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EXAMINER	DATE CONSIDERED	

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.